1.

Record Nr.	UNINA9910789648203321
Autore	Mahoney John <1931->
Titolo	Christianity in evolution [[electronic resource]] : an exploration / / Jack Mahoney
Pubbl/distr/stampa	Washington, D.C., : Georgetown University Press, c2011
ISBN	1-58901-799-4
Descrizione fisica	1 online resource (203 p.)
Disciplina	231.7/652
Soggetti	Evolution - Religious aspects - Catholic Church
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
Nota di contenuto	Accepting evolution -- Evolution, altruism, and the image of God -- The evolutionary achievement of Jesus -- Incarnation without the Fall -- Seeking a new paradigm -- The Church and the eucharist in evolution -- Theology in evolution.
Sommario/riassunto	Evolution has provided a new understanding of reality, with revolutionary consequences for Christianity. In an evolutionary perspective the incarnation involved God entering the evolving human species to help it imitate the trinitarian altruism in whose image it was created and counter its tendency to self-absorption. Primarily, however, the evolutionary achievement of Jesus was to confront and overcome death in an act of cosmic significance, ushering humanity into the culminating stage of its evolutionary destiny, the full sharing of God's inner life. Previously such doctrines as original sin

2.	Record Nr.	UNINA9910163046303321
	Titolo	3D Microelectronic Packaging : From Fundamentals to Applications / / edited by Yan Li, Deepak Goyal
	Pubbl/distr/stampa	Cham : , : Springer International Publishing : , : Imprint : Springer, , 2017
	ISBN	3-319-44586-3
	Edizione	[1st ed. 2017.]
	Descrizione fisica	1 online resource (IX, 463 p. 331 illus., 253 illus. in color.)
	Collana	Springer Series in Advanced Microelectronics, , 1437-0387 ; ; 57
	Disciplina	621.381
	Soggetti	Electronics Microelectronics Optical materials Electronics - Materials Electronic circuits Biotechnology Nanotechnology Metals Electronics and Microelectronics, Instrumentation Optical and Electronic Materials Electronic Circuits and Devices Microengineering Nanotechnology and Microengineering Metallic Materials
	Lingua di pubblicazione	Inglese
	Formato	Materiale a stampa
	Livello bibliografico	Monografia
	Nota di bibliografia	Includes bibliographical references and index.
	Nota di contenuto	Introduction to 3D Microelectronic Packaging.-3D packaging architecture and assembly process design.-Materials and Processing of TSV.-Microstructural and Reliability Issues of TSV -- Fundamentals and failures in Die preparation for 3D packaging.-Direct Cu to Cu bonding and other alternative bonding techniques in 3D packaging -- Fundamental of Thermal Compression Bonding Technology and Process Materials for 2.5/3D Packages -- Fundamentals of solder alloys in 3D packaging.-Fundamentals of Electromigration in interconnects of 3D

packages.-Fundamentals of heat dissipation in 3D IC packaging -- Fundamentals of advanced materials and processes in organic substrate technology -- Die and Package Level Thermal and Thermal/Moisture Stresses in 3-D Packaging: Modeling and Characterization -- Processing and Reliability of Solder Interconnections in Stacked Packaging -- Interconnect Quality and Reliability of 3D Packaging -- Fault isolation and failure analysis of 3D packaging. .

Sommario/riassunto

This volume provides a comprehensive reference for graduate students and professionals in both academia and industry on the fundamentals, processing details, and applications of 3D microelectronic packaging, an industry trend for future microelectronic packages. Chapters written by experts cover the most recent research results and industry progress in the following areas: TSV, die processing, micro bumps, direct bonding, thermal compression bonding, advanced materials, heat dissipation, thermal management, thermal mechanical modeling, quality, reliability, fault isolation, and failure analysis of 3D microelectronic packages. Numerous images, tables, and didactic schematics are included throughout. This essential volume equips readers with an in-depth understanding of all aspects of 3D packaging, including packaging architecture, processing, thermal mechanical and moisture related reliability concerns, common failures, developing areas, and future challenges, providing insights into key areas for future research and development. Provides comprehensive coverage of the state-of-the-art in 3D microelectronic packages Covers advanced materials and processes, quality and reliability concerns, and fault isolation and failure analysis Discusses 3D electronic package architecture and assembly process design Features contributions from both academic and industry authors, for a complete view of this important technology.